



---

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION**

Generic Copy

---

**Issue Date**  
**27-Oct-2006**

**SUBJECT: ON Semiconductor Final Product/Process Change Notification #15665**

**TITLE: Final PCN for Qualification of QFN 0.75 mm package thickness (1.2 x 1mm to 8x8mm, 6 to 52LD) at ON Seremban**

**PROPOSED FIRST SHIP DATE: 27-Dec-2006**

**AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly and Test Site**

**AFFECTED PRODUCT DIVISION(S): ON Semiconductor**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or:

**Edwin Soto** [Edwin.Soto@onsemi.com](mailto:Edwin.Soto@onsemi.com)

**Steven Black** [s.black@onsemi.com](mailto:s.black@onsemi.com)

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or [Laura.Rivers@onsemi.com](mailto:Laura.Rivers@onsemi.com)

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

This is a Final Product Change Notice to IPCN 15174 available at [www.onsemi.com](http://www.onsemi.com) to make customers aware that the ON Semiconductor facility in Seremban, Malaysia is being qualified as a manufacturing source for the ON WQFN packages.

ON Semiconductor, Seremban will provide assembly for COL packages: WQFN1826-16L, WQFN1418-10L, WQFN3010-12L & WQFN1012-6L for Analog, Logic, Discrete, TMOS, and High Frequency products and QFN (DFN2020-6L) uCool Packaged MOSFET products. Testing of these products will be performed by ON Semiconductor Seremban, Malaysia facility.

The affected QFN packages are being qualified to run specific devices that are currently processed in NSEB, Thailand. This is not a transfer but a capacity expansion.

**Final Product/Process Change Notification #15665****RELIABILITY DATA SUMMARY:**

<b>Test</b>	<b>Conditions</b>	<b>Results (Rej / SS)</b>
PC	24 hours bake@125C+ 168hr, 85C/85%RH+ 3X IR @ 260 °C +1flux immersion + alcohol + DI H2O rinse.	0/84, 0/84, 0/84
AC - PC	121°C/100% RH/15psig Post PC Electrical 96 Hrs	0/84, 0/84, 0/84 0/84, 0/84, 0/84
TC – PC	Ta=-65/+150deg.C, Air to air, Dwell = 10 min. Post PC Electrical 500 Cycles	0/84, 0/84, 0/84 0/84, 0/84, 0/84
HTSL	Ta=131deg.C 1008 Hrs	0/84, 0/84, 0/84
HAST	Ta=131deg.C, 85% RH/18.8psig 96 Hrs	0/84, 0/84, 0/84
RSH	Ta=260deg.C	0/35, 0/35, 0/35

**ELECTRICAL CHARACTERISTIC SUMMARY:**

All product performance meets current datasheet specifications. Data is available upon request.

**CHANGED PART IDENTIFICATION:**

Part traceability to manufacturing site will follow standard SOP. Parts with a date code of 0642 or greater may be manufactured at either site.



**Final Product/Process Change Notification #15665**

**AFFECTED DEVICE LIST:**

**PART**

NLAS3799BLMNR2G  
NLAS3799BMNR2G  
NLAS3799LMNR2G  
NLAS3799MNR2G  
NLAS4717EPMTR2G  
NLAS5123MNR2G  
NLAS5223BLMNR2G  
NLAS5223BMNR2G  
NLAS5223LMNR2G  
NLAS5223MNR2G  
NLAS9134MTR2G  
NLAS9431MTR2G  
NLAB3157MTR2G  
NTLJD3115PT1G  
NTLJD3115PTAG  
NTLJD4116NT1G  
NTLJF3117PT1G  
NTLJF4156NT1G  
NTLJF4156NTAG  
NTLJS3113PT1G  
NTLJS4159NT1G